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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1057
Number of Logic Elements/Cells	10570
Total RAM Bits	920448
Number of I/O	335
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA, FCBGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s10f484c5



About This Handbook

This handbook provides comprehensive information about the Altera® Stratix family of devices.

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- The Adobe Acrobat Find feature, which searches the text of a PDF document. Click the binoculars toolbar icon to open the Find dialog box.
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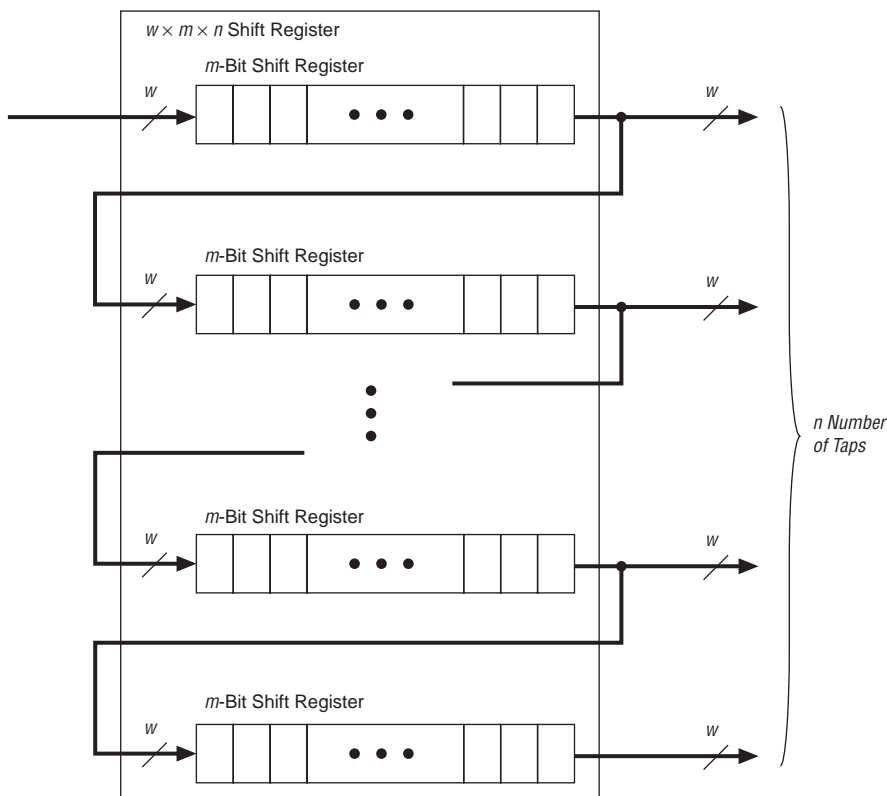
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Shift Register Support

You can configure embedded memory blocks to implement shift registers for DSP applications such as pseudo-random number generators, multi-channel filtering, auto-correlation, and cross-correlation functions. These and other DSP applications require local data storage, traditionally implemented with standard flip-flops, which can quickly consume many logic cells and routing resources for large shift registers. A more efficient alternative is to use embedded memory as a shift register block, which saves logic cell and routing resources and provides a more efficient implementation with the dedicated circuitry.

The size of a $w \times m \times n$ shift register is determined by the input data width (w), the length of the taps (m), and the number of taps (n). The size of a $w \times m \times n$ shift register must be less than or equal to the maximum number of memory bits in the respective block: 576 bits for the M512 RAM block and 4,608 bits for the M4K RAM block. The total number of shift register outputs (number of taps $n \times$ width w) must be less than the maximum data width of the RAM block (18 for M512 blocks, 36 for M4K blocks). To create larger shift registers, the memory blocks are cascaded together.

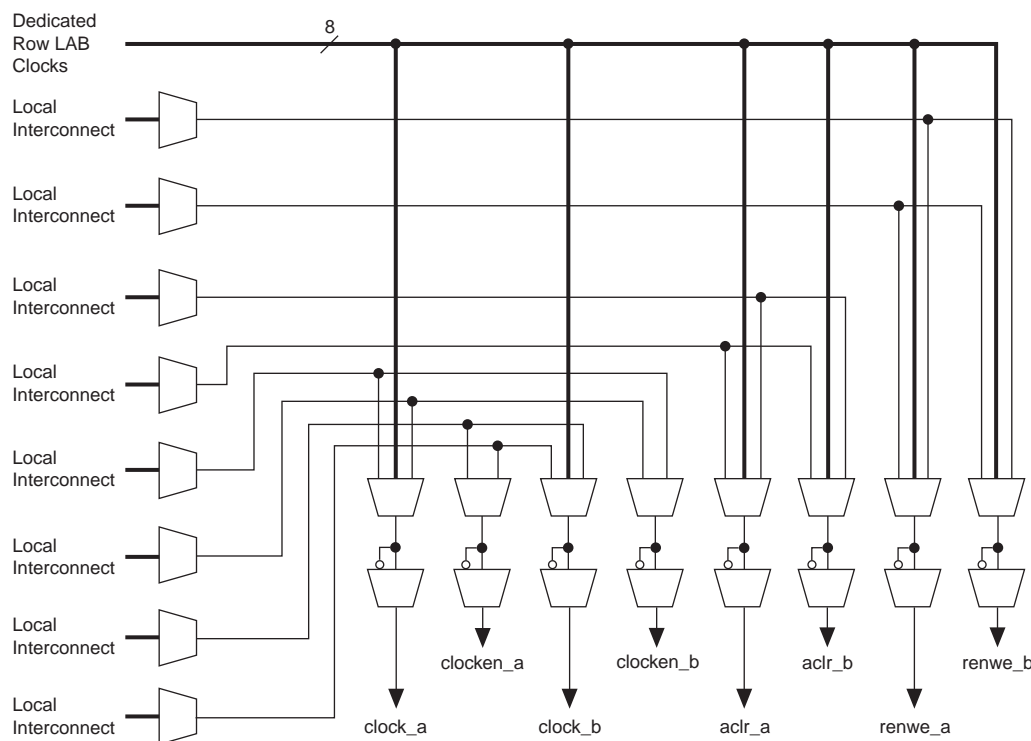
Data is written into each address location at the falling edge of the clock and read from the address at the rising edge of the clock. The shift register mode logic automatically controls the positive and negative edge clocking to shift the data in one clock cycle. [Figure 2-14](#) shows the TriMatrix memory block in the shift register mode.

Figure 2–14. Shift Register Memory Configuration

Memory Block Size

TriMatrix memory provides three different memory sizes for efficient application support. The large number of M512 blocks are ideal for designs with many shallow first-in first-out (FIFO) buffers. M4K blocks provide additional resources for channelized functions that do not require large amounts of storage. The M-RAM blocks provide a large single block of RAM ideal for data packet storage. The different-sized blocks allow Stratix devices to efficiently support variable-sized memory in designs.

The Quartus II software automatically partitions the user-defined memory into the embedded memory blocks using the most efficient size combinations. You can also manually assign the memory to a specific block size or a mixture of block sizes.

Figure 2–19. M-RAM Block Control Signals

One of the M-RAM block's horizontal sides drive the address and control signal (clock, renwe, byteena, etc.) inputs. Typically, the horizontal side closest to the device perimeter contains the interfaces. The one exception is when two M-RAM blocks are paired next to each other. In this case, the side of the M-RAM block opposite the common side of the two blocks contains the input interface. The top and bottom sides of any M-RAM block contain data input and output interfaces to the logic array. The top side has 72 data inputs and 72 data outputs for port B, and the bottom side has another 72 data inputs and 72 data outputs for port A. [Figure 2–20](#) shows an example floorplan for the EP1S60 device and the location of the M-RAM interfaces.

Table 2–13 shows the number of DSP blocks in each Stratix device.

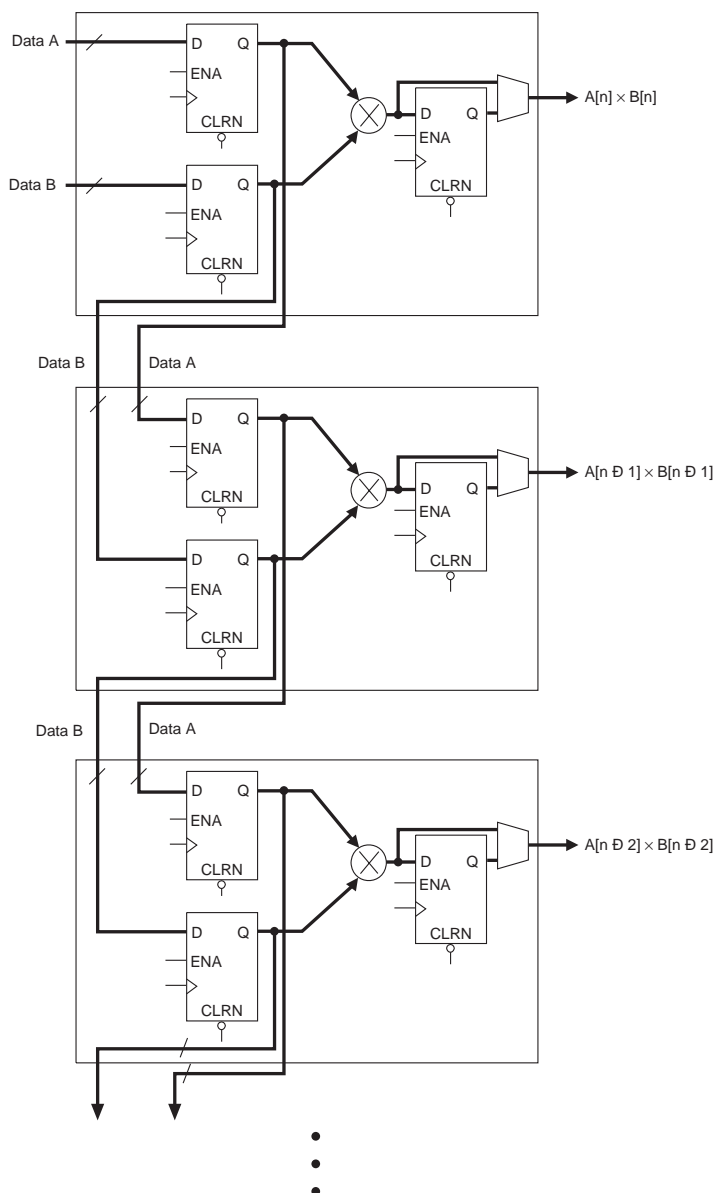
Table 2–13. DSP Blocks in Stratix Devices <i>Notes (1), (2)</i>				
Device	DSP Blocks	Total 9×9 Multipliers	Total 18×18 Multipliers	Total 36×36 Multipliers
EP1S10	6	48	24	6
EP1S20	10	80	40	10
EP1S25	10	80	40	10
EP1S30	12	96	48	12
EP1S40	14	112	56	14
EP1S60	18	144	72	18
EP1S80	22	176	88	22

Notes to Table 2–13:

- (1) Each device has either the number of 9×9 -, 18×18 -, or 36×36 -bit multipliers shown. The total number of multipliers for each device is not the sum of all the multipliers.
- (2) The number of supported multiply functions shown is based on signed/signed or unsigned/unsigned implementations.

DSP block multipliers can optionally feed an adder/subtractor or accumulator within the block depending on the configuration. This makes routing to LEs easier, saves LE routing resources, and increases performance, because all connections and blocks are within the DSP block. Additionally, the DSP block input registers can efficiently implement shift registers for FIR filter applications.

Figure 2–30 shows the top-level diagram of the DSP block configured for 18×18 -bit multiplier mode. Figure 2–31 shows the 9×9 -bit multiplier configuration of the DSP block.

Figure 2–33. Multiplier Sub-Blocks Using Input Shift Register Connections*Note (1)***Note to Figure 2–33:**

- (1) Either Data A or Data B input can be set to a parallel input for constant coefficient multiplication.

Table 2–14 shows the summary of input register modes for the DSP block.

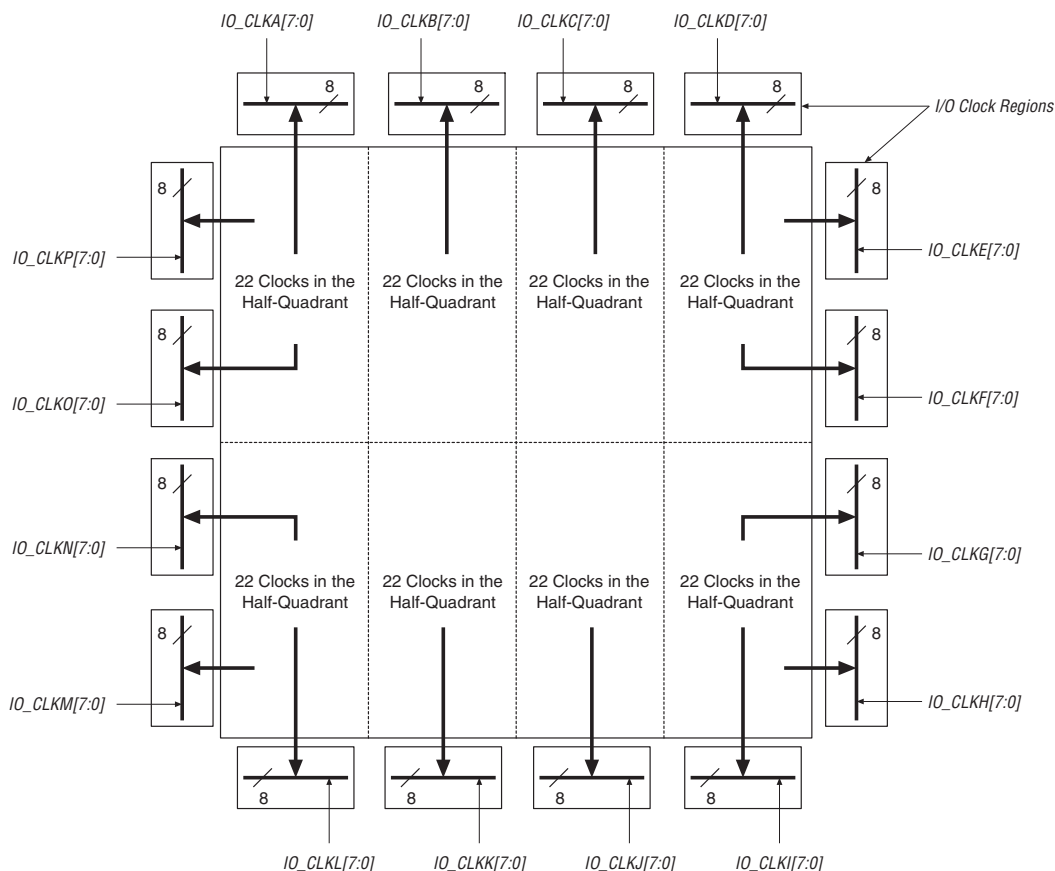
Table 2–14. Input Register Modes			
Register Input Mode	9 × 9	18 × 18	36 × 36
Parallel input	✓	✓	✓
Shift register input	✓	✓	

Multiplier

The multiplier supports 9 × 9-, 18 × 18-, or 36 × 36-bit multiplication. Each DSP block supports eight possible 9 × 9-bit or smaller multipliers. There are four multiplier blocks available for multipliers larger than 9 × 9 bits but smaller than 18 × 18 bits. There is one multiplier block available for multipliers larger than 18 × 18 bits but smaller than or equal to 36 × 36 bits. The ability to have several small multipliers is useful in applications such as video processing. Large multipliers greater than 18 × 18 bits are useful for applications such as the mantissa multiplication of a single-precision floating-point number.

The multiplier operands can be signed or unsigned numbers, where the result is signed if either input is signed as shown in Table 2–15. The `sign_a` and `sign_b` signals provide dynamic control of each operand's representation: a logic 1 indicates the operand is a signed number, a logic 0 indicates the operand is an unsigned number. These sign signals affect all multipliers and adders within a single DSP block and you can register them to match the data path pipeline. The multipliers are full precision (that is, 18 bits for the 18-bit multiply, 36-bits for the 36-bit multiply, and so on) regardless of whether `sign_a` or `sign_b` set the operands as signed or unsigned numbers.

Table 2–15. Multiplier Signed Representation		
Data A	Data B	Result
Unsigned	Unsigned	Unsigned
Unsigned	Signed	Signed
Signed	Unsigned	Signed
Signed	Signed	Signed

Figure 2–48. EP1S30, EP1S40, EP1S60, EP1S80 Device I/O Clock Groups

You can use the Quartus II software to control whether a clock input pin is either global, regional, or fast regional. The Quartus II software automatically selects the clocking resources if not specified.

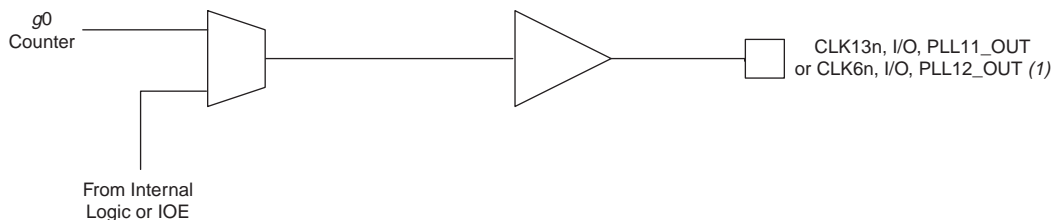
Enhanced & Fast PLLs

Stratix devices provide robust clock management and synthesis using up to four enhanced PLLs and eight fast PLLs. These PLLs increase performance and provide advanced clock interfacing and clock-frequency synthesis. With features such as clock switchover, spread spectrum clocking, programmable bandwidth, phase and delay control, and PLL reconfiguration, the Stratix device's enhanced PLLs provide you with complete control of your clocks and system timing. The fast PLLs

Table 2–20. I/O Standards Supported for Enhanced PLL Pins (Part 2 of 2)

I/O Standard	Input			Output
	INCLK	FBIN	PLENABLE	EXTCLK
1.5-V HSTL Class II	✓	✓		✓
1.8-V HSTL Class I	✓	✓		✓
1.8-V HSTL Class II	✓	✓		✓
SSTL-18 Class I	✓	✓		✓
SSTL-18 Class II	✓	✓		✓
SSTL-2 Class I	✓	✓		✓
SSTL-2 Class II	✓	✓		✓
SSTL-3 Class I	✓	✓		✓
SSTL-3 Class II	✓	✓		✓
AGP (1× and 2×)	✓	✓		✓
CTT	✓	✓		✓

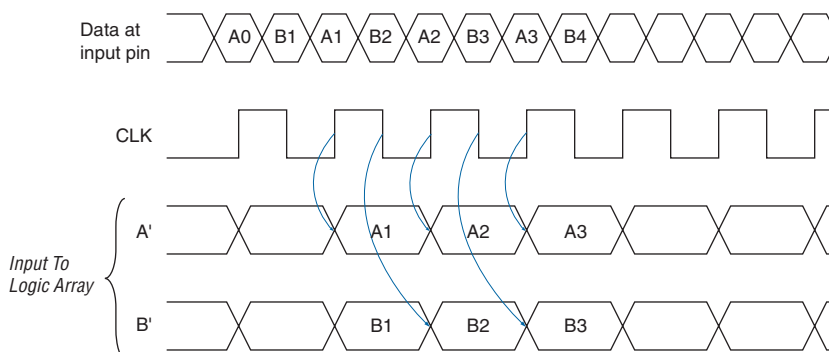
Enhanced PLLs 11 and 12 support one single-ended output each (see [Figure 2–56](#)). These outputs do not have their own VCC and GND signals. Therefore, to minimize jitter, do not place switching I/O pins next to this output pin.

Figure 2–56. External Clock Outputs for Enhanced PLLs 11 & 12

Note to Figure 2–56:

(1) For PLL 11, this pin is CLK13n; for PLL 12 this pin is CLK7n.

Stratix devices can drive any enhanced PLL driven through the global clock or regional clock network to any general I/O pin as an external output clock. The jitter on the output clock is not guaranteed for these cases.

Figure 2–66. Input Timing Diagram in DDR Mode

When using the IOE for DDR outputs, the two output registers are configured to clock two data paths from LEs on rising clock edges. These output registers are multiplexed by the clock to drive the output pin at a $\times 2$ rate. One output register clocks the first bit out on the clock high time, while the other output register clocks the second bit out on the clock low time. [Figure 2–67](#) shows the IOE configured for DDR output. [Figure 2–68](#) shows the DDR output timing diagram.

Programmable Pull-Up Resistor

Each Stratix device I/O pin provides an optional programmable pull-up resistor during user mode. If this feature is enabled for an I/O pin, the pull-up resistor (typically 25 k Ω) weakly holds the output to the V_{CCIO} level of the output pin's bank. Table 2–30 shows which pin types support the weak pull-up resistor feature.

Table 2–30. Programmable Weak Pull-Up Resistor Support	
Pin Type	Programmable Weak Pull-Up Resistor
I/O pins	✓
CLK [15 . . 0]	
FCLK	✓
FPLL [7 . . 10] CLK	
Configuration pins	
JTAG pins	✓ (1)

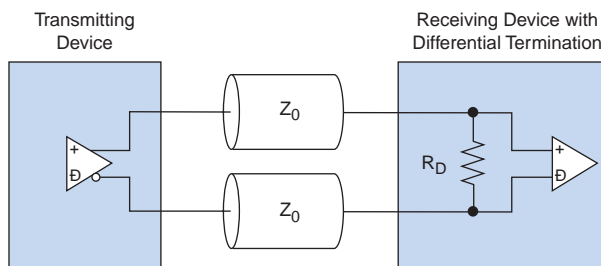
Note to Table 2–30:

(1) TDO pins do not support programmable weak pull-up resistors.

Advanced I/O Standard Support

Stratix device IOEs support the following I/O standards:

- LVTTTL
- LVCMOS
- 1.5 V
- 1.8 V
- 2.5 V
- 3.3-V PCI
- 3.3-V PCI-X 1.0
- 3.3-V AGP (1× and 2×)
- LVDS
- LVPECL
- 3.3-V PCML
- HyperTransport
- Differential HSTL (on input/output clocks only)
- Differential SSTL (on output column clock pins only)
- GTL/GTL+
- 1.5-V HSTL Class I and II

Figure 2–71. LVDS Input Differential On-Chip Termination

I/O banks on the left and right side of the device support LVDS receiver (far-end) differential termination.

Table 2–33 shows the Stratix device differential termination support.

Table 2–33. Differential Termination Supported by I/O Banks			
Differential Termination Support	I/O Standard Support	Top & Bottom Banks (3, 4, 7 & 8)	Left & Right Banks (1, 2, 5 & 6)
Differential termination (1), (2)	LVDS		✓

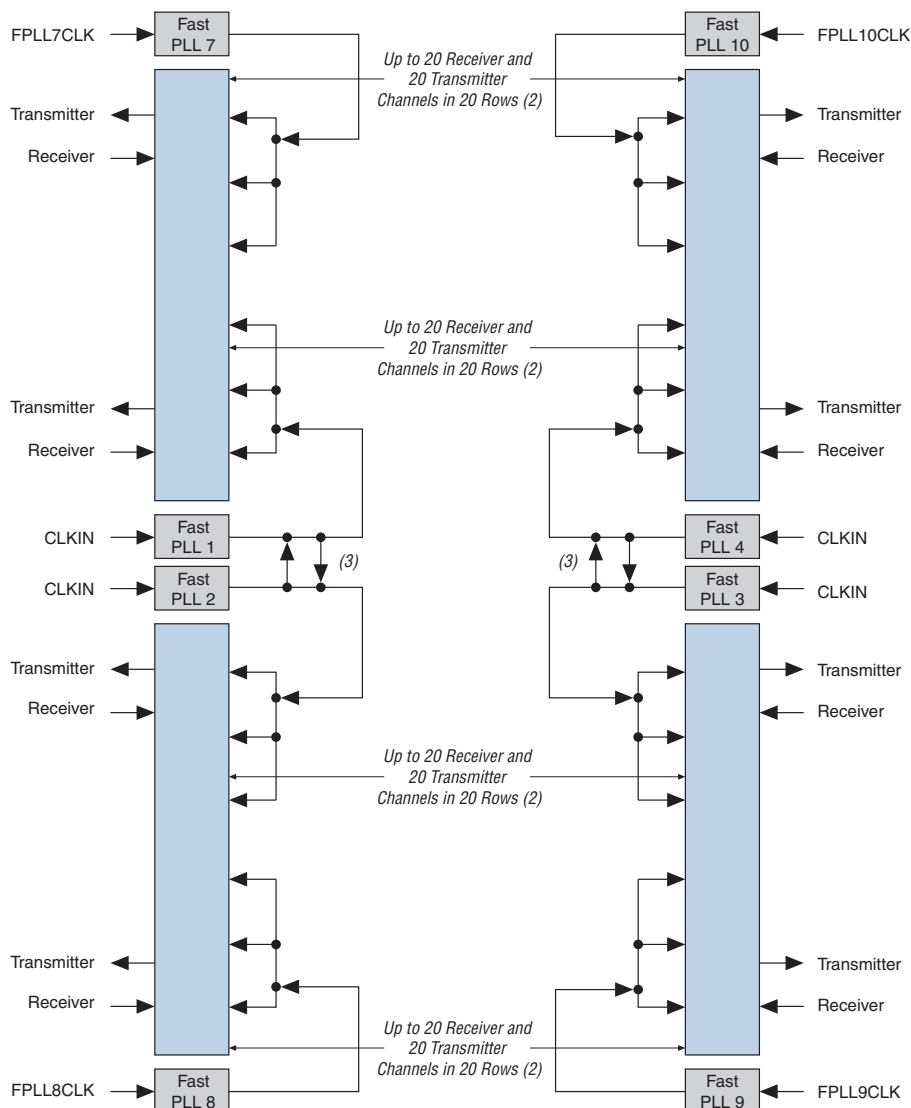
Notes to Table 2–33:

- (1) Clock pin CLK0, CLK2, CLK9, CLK11, and pins FPLL[7..10] CLK do not support differential termination.
- (2) Differential termination is only supported for LVDS because of a 3.3-V V_{CCIO} .

Table 2–34 shows the termination support for different pin types.

Table 2–34. Differential Termination Support Across Pin Types	
Pin Type	R_D
Top and bottom I/O banks (3, 4, 7, and 8)	
DIFFIO_RX[]	✓
CLK[0, 2, 9, 11], CLK[4–7], CLK[12–15]	
CLK[1, 3, 8, 10]	✓
FCLK	
FPLL[7..10] CLK	

The differential on-chip resistance at the receiver input buffer is $118\ \Omega \pm 20\%$.

Figure 2–75. Fast PLL & Channel Layout in the EP1S30 to EP1S80 Devices *Note (1)***Notes to Figure 2–75:**

- (1) Wire-bond packages support up to 624 Mbps.
- (2) See Table 2–38 through 2–41 for the number of channels each device supports.
- (3) There is a multiplexer here to select the PLL clock source. If a PLL uses this multiplexer to clock channels outside of its bank quadrant, those clocked channels support up to 840 Mbps for “high” speed channels and 462 Mbps for “low” speed channels as labeled in the device pin-outs at www.altera.com.

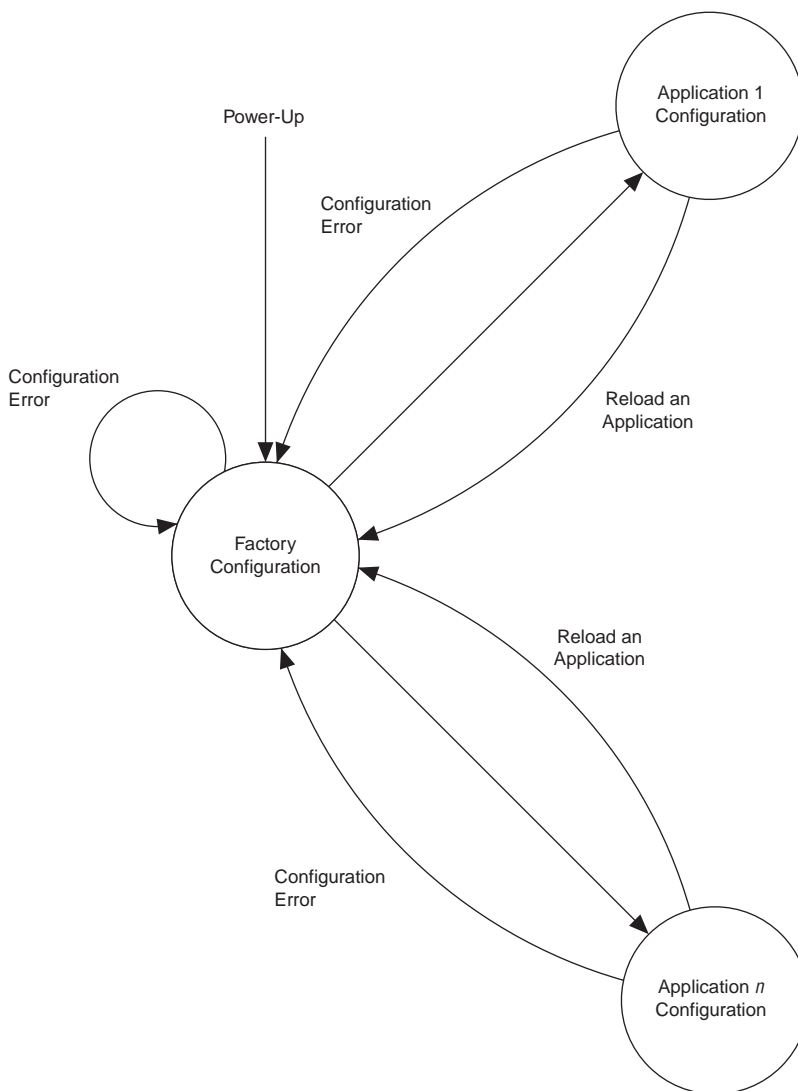
While in the factory configuration, the factory-configuration logic performs the following operations:

- Loads a remote update-control register to determine the page address of the new application configuration
- Determines whether to enable a user watchdog timer for the application configuration
- Determines what the watchdog timer setting should be if it is enabled

The user watchdog timer is a counter that must be continually reset within a specific amount of time in the user mode of an application configuration to ensure that valid configuration occurred during a remote update. Only valid application configurations designed for remote update can reset the user watchdog timer in user mode. If a valid application configuration does not reset the user watchdog timer in a specific amount of time, the timer updates a status register and loads the factory configuration. The user watchdog timer is automatically disabled for factory configurations.

If an error occurs in loading the application configuration, the configuration logic writes a status register to specify the cause of the error. Once this occurs, the Stratix device automatically loads the factory configuration, which reads the status register and determines the reason for reconfiguration. Based on the reason, the factory configuration will take appropriate steps and will write the remote update control register to specify the next application configuration page to be loaded.

When the Stratix device successfully loads the application configuration, it enters into user mode. The Stratix device then executes the main application of the user. Intellectual property (IP), such as a Nios® (16-bit ISA) and Nios® II (32-bit ISA) embedded processors, can help the Stratix device determine when remote update is coming. The Nios embedded processor or user logic receives incoming data, writes it to the configuration device, and loads the factory configuration. The factory configuration will read the remote update status register and determine the valid application configuration to load. [Figure 3–2](#) shows the Stratix remote update. [Figure 3–3](#) shows the transition diagram for remote update mode.

Figure 3–3. Remote Update Transition Diagram *Notes (1), (2)***Notes to Figure 3–3:**

- (1) Remote update of Application Configuration is controlled by a Nios embedded processor or user logic programmed in the Factory or Application configurations.
- (2) Up to seven pages can be specified allowing up to seven different configuration applications.

Table 4–39. DSP Block Internal Timing Microparameter Descriptions

Symbol	Parameter
t_{SU}	Input, pipeline, and output register setup time before clock
t_H	Input, pipeline, and output register hold time after clock
t_{CO}	Input, pipeline, and output register clock-to-output delay
$t_{INREG2PIPE9}$	Input Register to DSP Block pipeline register in 9×9 -bit mode
$t_{INREG2PIPE18}$	Input Register to DSP Block pipeline register in 18×18 -bit mode
$t_{PIPE2OUTREG2ADD}$	DSP Block Pipeline Register to output register delay in Two-Multipliers Adder mode
$t_{PIPE2OUTREG4ADD}$	DSP Block Pipeline Register to output register delay in Four-Multipliers Adder mode
t_{PD9}	Combinatorial input to output delay for 9×9
t_{PD18}	Combinatorial input to output delay for 18×18
t_{PD36}	Combinatorial input to output delay for 36×36
t_{CLR}	Minimum clear pulse width
t_{CLKHL}	Register minimum clock high or low time. This is a limit on the min time for the clock on the registers in these blocks. The actual performance is dependent upon the internal point-to-point delays in the blocks and may give slower performance as shown in Table 4–36 on page 4–20 and as reported by the timing analyzer in the Quartus II software.

Table 4–49. M4K Block Internal Timing Microparameters

Symbol	-5		-6		-7		-8		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{M4KRC}		3,807		4,320		4,967		5,844	ps
t_{M4KWC}		2,556		2,840		3,265		3,842	ps
$t_{M4KWRESU}$	131		149		171		202		ps
$t_{M4KWEREH}$	34		38		43		51		ps
$t_{M4KCLKENSU}$	193		215		247		290		ps
$t_{M4KCLKENH}$	–63		–70		–81		–95		ps
$t_{M4KBESU}$	131		149		171		202		ps
t_{M4KBEH}	34		38		43		51		ps
$t_{M4KDATAASU}$	131		149		171		202		ps
$t_{M4KDATAAH}$	34		38		43		51		ps
$t_{M4KADDRASU}$	131		149		171		202		ps
$t_{M4KADDRAH}$	34		38		43		51		ps
$t_{M4KDATABSU}$	131		149		171		202		ps
$t_{M4KDATA BH}$	34		38		43		51		ps
$t_{M4KADDRBSU}$	131		149		171		202		ps
$t_{M4KADDRBH}$	34		38		43		51		ps
$t_{M4KDATA CO1}$		571		635		729		858	ps
$t_{M4KDATA CO2}$		3,984		4,507		5,182		6,097	ps
$t_{M4KCLKHL}$	1,000		1,111		1,190		1,400		ps
t_{M4KCLR}	170		189		217		255		ps

Table 4–50. M-RAM Block Internal Timing Microparameters (Part 1 of 2)

Symbol	-5		-6		-7		-8		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{MRAMRC}		4,364		4,838		5,562		6,544	ps
t_{MRAMWC}		3,654		4,127		4,746		5,583	ps
$t_{MRAMWRESU}$	25		25		28		33		ps
$t_{MRAMWEREH}$	18		20		23		27		ps
$t_{MRAMCLKENSU}$	99		111		127		150		ps
$t_{MRAMCLKENH}$	–48		–53		–61		–72		ps

Table 4–119. Stratix Maximum Input Clock Rate for CLK[1, 3, 8, 10] Pins in Wire-Bond Packages (Part 2 of 2)

I/O Standard	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
SSTL-18 Class I	350	300	300	MHz
SSTL-18 Class II	350	300	300	MHz
1.5-V HSTL Class I	350	300	300	MHz
1.8-V HSTL Class I	350	300	300	MHz
CTT	250	200	200	MHz
Differential 1.5-V HSTL C1	350	300	300	MHz
LVPECL (1)	645	622	622	MHz
PCML (1)	275	275	275	MHz
LVDS (1)	645	622	622	MHz
HyperTransport technology (1)	500	450	450	MHz

Note to Tables 4–114 through 4–119:

(1) These parameters are only available on row I/O pins.

Tables 4–120 through 4–123 show the maximum output clock rate for column and row pins in Stratix devices.

Table 4–120. Stratix Maximum Output Clock Rate for PLL[5, 6, 11, 12] Pins in Flip-Chip Packages (Part 1 of 2)

I/O Standard	-5 Speed Grade	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
LVTTL	350	300	250	250	MHz
2.5 V	350	300	300	300	MHz
1.8 V	250	250	250	250	MHz
1.5 V	225	200	200	200	MHz
LVC MOS	350	300	250	250	MHz
GTL	200	167	125	125	MHz
GTL+	200	167	125	125	MHz
SSTL-3 Class I	200	167	167	133	MHz
SSTL-3 Class II	200	167	167	133	MHz
SSTL-2 Class I (3)	200	200	167	167	MHz
SSTL-2 Class I (4)	200	200	167	167	MHz
SSTL-2 Class I (5)	150	134	134	134	MHz

Table 4–132. Fast PLL Specifications for -7 Speed Grades (Part 2 of 2)

Symbol	Parameter	Min	Max	Unit
t_{JITTER}	Period jitter for DIFFIO clock out (6)		(5)	ps
t_{LOCK}	Time required for PLL to acquire lock	10	100	μs
m	Multiplication factors for m counter (7)	1	32	Integer
J0, I1, g0	Multiplication factors for J0, I1, and g0 counter (7), (8)	1	32	Integer
t_{ARESET}	Minimum pulse width on areset signal	10		ns

Table 4–133. Fast PLL Specifications for -8 Speed Grades (Part 1 of 2)

Symbol	Parameter	Min	Max	Unit
f_{IN}	CLKIN frequency (1), (3)	10	460	MHz
f_{INPFD}	Input frequency to PFD	10	500	MHz
f_{OUT}	Output frequency for internal global or regional clock (4)	9.375	420	MHz
$f_{\text{OUT_DIFFIO}}$	Output frequency for external clock driven out on a differential I/O data channel	(5)	(5)	MHz
f_{VCO}	VCO operating frequency	300	700	MHz
t_{INDUTY}	CLKIN duty cycle	40	60	%
t_{INJITTER}	Period jitter for CLKIN pin		± 200	ps
t_{DUTY}	Duty cycle for DIFFIO 1 \times CLKOUT pin (6)	45	55	%
t_{JITTER}	Period jitter for DIFFIO clock out (6)		(5)	ps
t_{LOCK}	Time required for PLL to acquire lock	10	100	μs
m	Multiplication factors for m counter (7)	1	32	Integer
J0, I1, g0	Multiplication factors for J0, I1, and g0 counter (7), (8)	1	32	Integer

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